# Semicondutor Process, Equipment and Materials

**Semicondutor Process, Equipment and Materials'** objective is to reinforce European manufacturing position by gaining leadership in processing know-how for advanced and beyond CMOS (More Moore, MM), heterogeneous (More than Moore, MtM) and System in Package (SiP) technology.

More in concrete, the aim is to  support the complete European value chain in process technology, materials and manufacturing equipment to realize advanced next generation devices as innovative products and as well to establish pilot lines in MM and MtM and supporting test beds to accelerate the uptake of KETs covering all essential aspects for short time-to-market (cost-efficiency, standards, test, etc.) in front and back-end wafer processing, device packaging and assembly.

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